

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

1 – 9. (Canceled)

10. (Currently amended): A method for manufacturing a front-and-back electrically conductive substrate, the method comprising the steps of:

preparing a wafer made of a single material having a thickness greater than a height of a plurality of posts to be formed;

forming, by a process of anisotropic etching, the plurality of posts having an electrically conductive portion; [[and]]

filling space between the plurality of posts with an insulating material, thereby obtaining a composite substrate having a first surface and a second surface; and

polishing the first surface and second surface to obtain the front-and-back electrically conductive substrate, wherein the first surface and second surface are electrically connected by the plurality of posts.

11. (Canceled)

12. (Original): The method for manufacturing the front-and-back electrically conductive substrate as claimed in claim 10, wherein the anisotropic etching process leaves a portion of the etching material disposed so as to couple the plurality of posts to each other.

13 – 16. (Canceled)

17. (Currently amended): A method for manufacturing a front-and-back electrically conductive substrate, the method comprising the steps of:

performing a process of anisotropic etching to a wafer so as to leave a plurality of posts;
[[and]]

filing space between the plurality of posts with an insulting material, thereby obtaining a composite substrate having a first surface and a second surface; and

polishing the first surface and second surface to obtain the front-and-back electrically conductive substrate, wherein the first surface and second surface are electrically connected by the plurality of posts.

18. (Currently amended): A method for manufacturing a front-and-back electrically conductive substrate, the method comprising the steps of:

Forming, by a process of anisotropic etching, a plurality of posts;

covering the plurality of posts with an electrically conductive layer; [[and]]

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filing space between the plurality of posts with an insulting material, thereby obtaining a composite substrate having a first surface and a second surface; and

polishing the first surface and second surface to obtain the front-and-back electrically conductive substrate, wherein the first surface and second surface are electrically connected by the plurality of posts.